## AMAXIM Voltage－Output，12－Bit DAC

＋5V，Low－Power，Parallel－Input，

## $\qquad$ <br> General Description

The MAX530 is a low－power，12－bit，voltage－output digi－ tal－to－analog converter（DAC）that uses single +5 V or dual $\pm 5 \mathrm{~V}$ supplies．This device has an on－chip voltage reference plus an output buffer amplifier．Operating cur－ rent is only $250 \mu \mathrm{~A}$ from a single +5 V supply，making it ideal for portable and battery－powered applications．In addition，the SSOP（Shrink－Small－Outline－Package）mea－ sures only 0.1 square inches，using less board area than an 8 －pin DIP．12－bit resolution is achieved through laser trimming of the DAC，op amp，and reference．No further adjustments are necessary．
Internal gain－setting resistors can be used to define a DAC output voltage range of 0 V to $+2.048 \mathrm{~V}, \mathrm{OV}$ to +4.096 V ，or $\pm 2.048 \mathrm{~V}$ ．Four－quadrant multiplication is pos－ sible without the use of external resistors or op amps．The parallel logic inputs are double buffered and are compati－ ble with 4 －bit， 8 －bit，and 16 －bit microprocessors．For DACs with similar features but with a serial data interface，refer to the MAX531／MAX538／MAX539 data sheet．

## Applications

Battery－Powered Data－Conversion Products Minimum Component－Count Analog Systems Digital Offset／Gain Adjustment Industrial Process Control Arbitrary Function Generators Automatic Test Equipment Microprocessor－Controlled Calibration

Functional Diagram

－Buffered Voltage Output
－Internal 2．048V Voltage Reference
－Operates from Single +5 V or Dual $\pm 5 \mathrm{~V}$ Supplies
－Low Power Consumption：
$250 \mu \mathrm{~A}$ Operating Current
40 A A Shutdown－Mode Current
－SSOP Package Saves Space
－Relative Accuracy：$\pm^{1 / 2}$ LSB Max Over Temperature
－Guaranteed Monotonic Over Temperature
－4－Quadrant Multiplication with No External Components
－Power－On Reset
－Double－Buffered Parallel Logic Inputs
Ordering Information

| PART | TEMP．RANGE | PIN－PACKAGE | ERROR <br> （LSB） |
| :---: | :---: | :--- | :---: |
| MAX530ACNG | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 Narrow Plastic DIP | $\pm 1 / 2$ |
| MAX530BCNG | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 Narrow Plastic DIP | $\pm 1$ |
| MAX530ACWG | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1 / 2$ |
| MAX530BCWG | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1$ |
| MAX530ACAG | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1 / 2$ |
| MAX530BCAG | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1$ |
| MAX530BC／D | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | Dice ${ }^{*}$ | $\pm 1$ |

Ordering Information continued on last page．
＊Dice are tested at $T_{A}=+25^{\circ} \mathrm{C}, D C$ parameters only．

## Pin Configuration



Maxim Integrated Products

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## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC

## ABSOLUTE MAXIMUM RATINGS

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Note 1: The output may be shorted to $\mathrm{V}_{\mathrm{DD}}, \mathrm{V}_{\mathrm{SS}}, \mathrm{DGND}$, or AGND if the continuous package power dissipation and current ratings are not exceeded. Typical short-circuit currents are 20 mA .
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## ELECTRICAL CHARACTERISTICS-Single +5 V Supply

$(\mathrm{VDD}=5 \mathrm{~V} \pm 10 \%, \mathrm{VSS}=0 \mathrm{~V}, \mathrm{AGND}=\mathrm{DGND}=\mathrm{REFGND}=0 \mathrm{~V}, \mathrm{REFIN}=2.048 \mathrm{~V}$ (external), RFB $=$ ROFS $=\mathrm{VOUT}, \mathrm{CREFOUT}=33 \mu \mathrm{~F}$, $\mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{L}}=100 \mathrm{pF}, \mathrm{TA}=$ TMIN to TMAX, unless otherwise noted.)


## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC

## ELECTRICAL CHARACTERISTICS-Single +5 V Supply (continued)

(VDD $=5 \mathrm{~V} \pm 10 \%, \mathrm{VSS}=0 \mathrm{~V}, \mathrm{AGND}=\mathrm{DGND}=\mathrm{REFGND}=0 \mathrm{~V}, \mathrm{REFIN}=2.048 \mathrm{~V}$ (external), RFB $=$ ROFS $=\mathrm{VOUT}$, CREFOUT $^{\mathrm{R}}=33 \mu \mathrm{~F}$ $R_{L}=10 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{L}}=100 \mathrm{pF}, \mathrm{T}_{\mathrm{A}}=\mathrm{T}_{\mathrm{MIN}}$ to $\mathrm{T}_{\mathrm{MAX}}$, unless otherwise noted.)


## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC

## ELECTRICAL CHARACTERISTICS—Dual $\pm 5 \mathrm{~V}$ Supplies

M $\mathrm{V}_{\mathrm{DD}}=5 \mathrm{~V} \pm 10 \%, \mathrm{~V} S=-5 \mathrm{~V} \pm 10 \%, \mathrm{AGND}=\mathrm{DGND}=\mathrm{REFGND}=0 \mathrm{~V}, \mathrm{REFIN}=2.048 \mathrm{~V}$ (external), RFB $=$ ROFS $=$ VOUT,
CREFOUT $=33 \mu \mathrm{~F}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{L}}=100 \mathrm{pF}, \mathrm{T}_{\mathrm{A}}=\mathrm{T}_{\mathrm{MIN}}$ to $\mathrm{T}_{\mathrm{MAX}}$, unless otherwise noted.)


# +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC 

## ELECTRICAL CHARACTERISTICS—Dual $\pm 5 \mathrm{~V}$ Supplies (continued)

$\left(V_{D D}=5 \mathrm{~V} \pm 10 \%, \mathrm{~V}_{S S}=-5 \mathrm{~V} \pm 10 \%, \mathrm{AGND}=\mathrm{DGND}=\mathrm{REFGND}=0 \mathrm{~V}, \mathrm{REFIN}=2.048 \mathrm{~V}\right.$ (external), RFB = ROFS = VOUT, $C_{\text {REFOUT }}=33 \mu \mathrm{~F}, \mathrm{R}_{\mathrm{L}}=10 \mathrm{k} \Omega, \mathrm{C}_{\mathrm{L}}=100 \mathrm{pF}, \mathrm{T}_{\mathrm{A}}=\mathrm{T}_{\mathrm{MIN}}$ to $\mathrm{T}_{\mathrm{MAX}}$, unless otherwise noted.)
Note 2: In single supply, INL and GE are calculated from code 11 to code 4095.
Note 3: Zero Code, Bipolar and Gain Error PSRR are input referred specifications. In Unity Gain, the specification is $500 \mu \mathrm{~V}$. In Gain = 2 and Bipolar modes, the specification is 1 mV .
Note 4: Guaranteed by design.
Note 5: $\mathrm{REFIN}=1 \mathrm{kHz}, 2.0 \mathrm{Vp}-\mathrm{p}$.
Note 6: For specified performance, $\mathrm{V}_{\mathrm{DD}}=5 \mathrm{~V} \pm 10 \%$ is guaranteed by PSRR tests.
Note 7: For specified performance, $\mathrm{V}_{\mathrm{SS}}=-5 \mathrm{~V} \pm 10 \%$ is guaranteed by PSRR tests.
Note 8: Tested at $\mathrm{I}_{\text {OUT }}=100 \mu \mathrm{~A}$. The reference can typically source up to 5 mA (see Typical Operating Characteristics).

Typical Operating Characteristics
$\left(T_{A}=+25^{\circ} \mathrm{C}\right.$, single supply $(+5 \mathrm{~V})$, unity gain, code $=$ all 1 s , unless otherwise noted).







## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC

## $\left(\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, single supply $(+5 \mathrm{~V})$, unity gain, code $=$ all 1 s , unless otherwise noted $)$.

Typical Operating Characteristics (continued)


GAIN AND PHASE vs.


DIGITAL FEEDTHROUGH


A: D0...D7 $=100 \mathrm{kHz}, 4 \mathrm{Vp}-\mathrm{p}$
B: VOUT, $10 \mathrm{mV} / \mathrm{div}$ $\overline{\mathrm{LDAC}}=\overline{\mathrm{CS}}=\mathrm{HIGH}$



SETTUNG TIME (RISING)


A: DIGITAL INPUTS RISINGEDGE
A: DIGITAL INPUTS RISING
B: VOUT, NOLOAD, 1V/div
B: VOU, NOLOAD,
DUAL SUPPLY ( $\pm 5 \mathrm{~V}$ )
DUAL SUPPLY
LDAC
BIPOLARCO


REFERENCE OUTPUT VOLTAGE vs. REFERENCE LOAD CURRENT


SETTLING TIME (FALLING)


A: DIGITAL INPUTS FALLINGEDGE $5 \mathrm{~V} / \mathrm{div}$
B: VOUT, NOLOAD, $1 \mathrm{~V} / \mathrm{div}$
UUA SUPPLY $( \pm 5 \mathrm{~V})$
LDAC = LOW
BIPOLAR OONFGURATION
$\mathrm{V}_{\text {R } \because \mathrm{A}} \mathrm{N}=2 \mathrm{~V}$

# +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC 

Pin Description

| PIN | NAME | FUNCTION |
| :---: | :---: | :---: |
| 1 | D1/D9 | D1 Input Dta, when A0 $=0$ and $\mathrm{A} 1=1$, or D9 Input when $\mathrm{A} 0=\mathrm{A} 1=1^{*}$ |
| 2 | D2/ D10 | D2 Input Dta, when $\mathrm{A} 0=0$ and $\mathrm{A} 1=1$, or D10 Input when $\mathrm{A} 0=\mathrm{A} 1=1^{*}$ |
| 3 | D3/ D11 | D3 Input Dta, when $\mathrm{A} 0=0$ and $\mathrm{A} 1=1$, or D 11 (MSB) Input when $\mathrm{A} 0=\mathrm{A} 1=1$ * |
| 4 | D4 | D4 Input Dta, or tie to D0 and multiplex when A0 = 1 and $\mathrm{A} 1=0$ * |
| 5 | D5 | D5 Input Dta, or tie to D1 and multiplex when A0 = 1 and $\mathrm{A} 1=0$ * |
| 6 | D6 | D6 Input Dta, or tie to D2 and multiplex when $\mathrm{A} 0=1$ and $\mathrm{A} 1=0^{*}$ |
| 7 | D7 | D7 Input Dta, or tie to D3 and multiplex when A0 $=1$ and A1 $=0^{*}$ |
| 8 | A0 | Address Line A0. With A1, used to multiplex 4 of 12 data lines to load low (NBL), middle (NBM), and high (NBH) 4 -bit nibbles. ( 12 bits can also be loaded as $8+4$.) |
| 9 | A1 | Address Line A 1 . Set $\mathrm{A} 0=\mathrm{A} 1=0$ for NBL and $\mathrm{NBM}, \mathrm{A} 0=0$ and $\mathrm{A} 1=1$ for $\mathrm{NBL}, \mathrm{A} 0=1$ and $\mathrm{A} 1=0$ for NBM , or $\mathrm{A} 0=\mathrm{A} 1=1$ for NBH . See Table 2 for complete input latch addressing. |
| 10 | WR | Write Input (active low). Used with $\overline{\mathrm{CS}}$ to load data into the input latch selected by A0 and A1. |
| 11 | $\overline{\mathrm{CS}}$ | Chip Select (active low). Enables addressing and writing to this chip from common bus lines. |
| 12 | DGND | Digital Ground |
| 13 | REFIN | Reference Input. Input for the R-2R DAC. Connect an external reference to this pin or a jumper to REFOUT (pin 18) to use the internal 2.048 V reference. |
| 14 | AGND | Analog Ground |
| 15 | $\overline{C L R}$ | Clear (active low). A low on $\overline{C L R}$ resets the DAC latches to all Os. |
| 16 | LDAC | Load DAC Input (active low). Driving this asynchronous input low transfers the contents of the input latch to the DAC latch and updates VOUT. |
| 17 | REFGND | Reference Ground must be connected to AGND when using the internal reference. Connect to VDD to disable the internal reference and save power. |
| 18 | REFOUT | Reference Output. Output of the internal 2.048 V reference. Tie to REFIN to drive the R-2R DAC. |
| 19 | VSS | Negative Power Supply. Usually ground for single-supply or -5V for dual-supply operation. |
| 20 | VOUT | Voltage Output. Op-amp buffered DAC output. |
| 21 | RFB | Feedback Pin. Op-amp feedback resistor. Always connect to VOUT. |
| 22 | ROFS | Offset Resistor Pin. Connect to VOUT for $\mathrm{G}=1$, to AGND for $\mathrm{G}=2$, or to REFIN for bipolar output. |
| 23 | VDD | Positive Power Supply ( +5 V ) |
| 24 | D0/D8 | D0 (LSB) Input Dta when A0 $=0$ and $\mathrm{A} 1=1$, or D8 Input when $\mathrm{A} 0=\mathrm{A} 1=1^{*}$ |

* This applies to $4+4+4$ input loading mode. See Table 2 for $8+4$ input loading mode.


## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC

## Detailed Description

The MAX530 consists of a parallel-input logic interface, a 12-bit R-2R ladder, a reference, and an op amp. The Functional Diagram shows the control lines and signal flow through the input data latch to the DAC latch, as well as the 2.048 V reference and output op amp. Total supply current is typically $250 \mu \mathrm{~A}$ with a single +5 V supply. This circuit is ideal for battery-powered, microprocessor-controlled applications where high accuracy, no adjustments, and minimum component count are key requirements.

## R-2R Ladder

The MAX530 uses an "inverted" R-2R ladder network with a BiCMOS op amp to convert 12-bit digital data to analog voltage levels. Figure 1 shows a simplified diagram of the R-2R DAC and op amp. Unlike a standard DAC, the MAX530 uses an "inverted" ladder network. Normally, the REFIN pin is the current output of a standard DAC and would be connected to the summing junction, or virtual ground, of an op amp. In this standard DAC configura-


Figure 1. Simplified MAX530 DAC Circuit
tion, however, the output voltage would be the inverse of the reference voltage. The MAX530's topology makes the ladder output voltage the same polarity as the reference input, which makes the device suitable for single-supply operation. The BiCMOS op amp is then used to buffer, invert, or amplify the ladder signal.
Ladder resistors are nominally $80 \mathrm{k} \Omega$ to conserve power and are laser trimmed for gain and linearity. The input impedance at REFIN is code dependent. When the DAC register is all 0 s , all rungs of the ladder are grounded and REFIN is open or no load. Maximum loading (minimum REFIN impedance) occurs at code 010101... or 555hex. Minimum reference input impedance at this code is guaranteed to be not less than $40 \mathrm{k} \Omega$.
The REFIN and REFOUT pins allow the user to choose between driving the $\mathrm{R}-2 \mathrm{R}$ ladder with the on-chip reference or an external reference. REFIN may be below analog ground when using dual supplies. See the External Reference and Four-Quadrant Multiplication sections for more information.

Internal Reference
The on-chip reference is laser trimmed to generate 2.048 V at REFOUT. The output stage can source and sink current so REFOUT can settle to the correct voltage quickly in response to code-dependent loading changes. Typically source current is 5 mA and sink current is $100 \mu \mathrm{~A}$.
REFOUT connects the internal reference to the R-2R DAC ladder at REFIN. The R-2R ladder draws $50 \mu \mathrm{~A}$ maximum load current. If any other connection is made to REFOUT, ensure that the total load current is less than $100 \mu \mathrm{~A}$ to avoid gain errors.
A separate REFGND pin is provided to isolate reference currents from other analog and digital ground currents. To achieve specified noise performance, connect a $33 \mu \mathrm{~F}$ capacitor from REFOUT to REFGND (see Figure 2). Using smaller capacitance values increases noise, and values less than $3.3 \mu \mathrm{~F}$ may compromise the reference's stability. For applications requiring the lowest noise, insert a buffered RC filter between REFOUT and REFIN. When using the internal reference, REFGND must be connected to AGND. In applications not requiring the internal reference, connect REFGND to $V_{D D}$, which shuts down the reference and saves typically $100 \mu \mathrm{~A}$ of $\mathrm{V}_{D D}$ supply current.

# +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC 



Figure 2. Reference Noise vs. Frequency

## Output Buffer

The output amplifier uses a folded cascode input stage and a type AB output stage. Large output devices with low series resistance allow the output to swing to ground in single-supply operation. The output buffer is unity-gain stable. Input offset voltage and supply current are laser trimmed. Settling time is $25 \mu \mathrm{~s}$ to $0.01 \%$ of final value. The output is short-circuit protected and can drive a $2 \mathrm{k} \Omega$ load with more than 100 pF of load capacitance. The op amp may be placed in unity-gain ( $G=1$ ), in a gain of two ( $G=2$ ), or in a bipolar-output mode by using the ROFS and RFB pins. These pins are used to define a DAC output voltage range of 0 V to $+2.048 \mathrm{~V}, 0 \mathrm{~V}$ to +4.096 V or $\pm 2.048 \mathrm{~V}$, by connecting ROFS to VOUT, GND, or REFIN. RFB is always connected to VOUT. Table 1 summarizes ROFS usage.

Table 1. ROFS Usage

| ROFS <br> CONNECTED TO: | DAC OUTPUT <br> RANGE | OP-AMP <br> GAIN |
| :---: | :---: | :---: |
| VOUT | 0 V to 2.048 V | $\mathrm{G}=1$ |
| AGND | 0 V to 4.096 V | $\mathrm{G}=2$ |
| REFIN | -2.048 V to +2.048 V | Bipolar |

Note: Assumes RFB $=$ VOUT and REFIN $=$ REFOUT $=2.048 \mathrm{~V}$

## External Reference

An external reference in the range (VSS +2 V ) to ( $V_{D D}-2 \mathrm{~V}$ ) may be used with the MAX530 in dual-supply, unity-gain operation. In single-supply, unity-gain operation, the reference must be positive and may not exceed ( $V_{D D}-2 \mathrm{~V}$ ). The reference voltage determines the DAC's full-scale output. Because of the codedependent nature of reference input impedances, a high-quality, low-output-impedance amplifier (such as the MAX480 low-power, precision op amp) should be used to drive REFIN.
If an upgrade to the internal reference is required, the 2.5V MAX873A is ideal: $\pm 15 \mathrm{mV}$ initial accuracy, $7 \mathrm{ppm} /{ }^{\circ} \mathrm{C}$ (max) temperature coefficient.

## Power-On Reset

An internal power-on reset (POR) circuit forces the DAC register to reset to all 0 s when VDD is first applied. The POR pulse is typically $1.3 \mu \mathrm{~s}$; however, it may take 2 ms for the internal reference to charge its large filter capacitor and settle to its trimmed value.
In addition to POR, a clear ( $\overline{\mathrm{CLR}}$ ) pin, when held low, sets the DAC register to all Os. CLR operates asynchronously and independently from chip select (CS). With the DAC input at all 0 s , the op-amp output is at zero for unity-gain and $G=2$ configurations, but it is at -VREF for the bipolar configuration.

## Shutdown Mode

The MAX530 is designed for low power consumption. Understanding the circuit allows power consumption management for maximum efficiency. In single-supply mode (VDD $=+5 \mathrm{~V}$, VSS $=$ GND $)$ the initial supply current is typically only $160 \mu \mathrm{~A}$, including the reference, op amp, and DAC. This low current occurs when the power-on reset circuit clears the DAC to all Os and forces the op-amp output to zero (unipolar mode only). See the Supply Current vs. REFIN graph in the Typical Operating Characteristics. Under this condition, there is no internal load on the reference (DAC $=000$ hex, REFIN is open circuit) and the op amp operates at its minimum quiescent current. The CLR signal resets the MAX530 to these same conditions and can be used to control a power-saving mode when the DAC is not being used by the system.

## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC



Figure 3. Low-Current Shutdown Mode

An additional $110 \mu \mathrm{~A}$ of supply current can be saved when the internal reference is not used by connecting REFGND to VDD. A low on resistance N-channel FET, such as the 2N7002, can be used to turn off the internal reference to create a shutdown mode with minimum current drain (Figure 3). When CLR is high, the transistor pulls REFGND to AGND and the reference and DAC operate normally. When CLR goes low, REFGND is pulled up to $V_{D D}$ and the reference is shut down. At the same time, CLR resets the DAC register to all 0 s , and the op-amp output goes to 0 V for unity-gain and $\mathrm{G}=2$
Table 2. Input Latch Addressing

| $\overline{\text { CLR }}$ | $\overline{\text { CS }}$ | WR | $\overline{\text { LDAC }}$ | A0 | A1 | DATA UPDATED |
| :---: | :---: | :---: | :---: | :---: | :---: | :--- |
| L | X | X | X | X | X | Reset DAC Latches |
| H | H | X | H | X | X | No Operation |
| H | X | H | H | X | X | No Operation |
| H | L | L | H | H | H | NBH (D8-D11) |
| H | L | L | H | H | L | NBM (D4-D7) |
| H | L | L | H | L | H | NBL (D0-D3) |
| H | H | H | L | X | X | Update DAC Only |
| H | L | L | X | L | L | DAC NOT UPDATED |
| H | L | L | L | H | H | NBH and Update DAC |

modes. This reduces the total single-supply operating current from $250 \mu \mathrm{~A}(400 \mu \mathrm{~A}$ max) to typically $40 \mu \mathrm{~A}$ in shutdown mode.
A small error voltage is added to the reference output by the reference current flowing through the N-channel pull-down transistor. The switch's on resistance should be less than $5 \Omega$. A typical reference current of $100 \mu \mathrm{~A}$ would add 0.5 mV to REFOUT. Since the reference current and on resistance increase with temperature, the overall temperature coefficient will degrade slightly.
As data is loaded into the DAC and the output moves above GND, the op-amp quiescent current increases to its nominal value and the total operating current averages $250 \mu \mathrm{~A}$. Using dual supplies ( $\pm 5 \mathrm{~V}$ ), the op amp is fully biased continuously, and the VDD supply current is more constant at $250 \mu \mathrm{~A}$. The $\mathrm{V}_{\text {SS }}$ current is typically $150 \mu \mathrm{~A}$.
The MAX530 logic inputs are compatible with TTL and CMOS logic levels. However, to achieve the lowest power dissipation, drive the digital inputs with rail-to-rail CMOS logic. With TTL logic levels, the power requirement increases by a factor of approximately 2.

## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC



Figure 4. MAX530 Write-Cycle Timing Diagram

Parallel Logic Interface
Designed to interface with 4-bit, 8-bit, and 16-bit microprocessors ( $\mu \mathrm{Ps}$ ), the MAX530 uses 8 data pins and double-buffered logic inputs to load data as $4+4+4$ or $8+4$. The 12 -bit DAC latch is updated simultaneously through the control signal LDAC. Signals A0, A1, WR, and CS select which input latches to update. The 12-bit data is broken down into nibbles (NB); NBL is the enable signal for the lowest 4 bits, NBM is the enable for the middle 4 bits, and NBH is the enable for the highest and most significant 4 bits. Table 2 lists the address decoding scheme.
Refer to Figure 4 for the MAX530 write-cycle timing diagram.
Figure 5 shows the circuit configuration for a 4 -bit $\mu \mathrm{P}$ application. Figure 6 shows the corresponding timing sequence. The 4 low bits (DO-D3) are connected in parallel to the other 4 bits (D4-D7) and then to the $\mu \mathrm{P}$ bus. Address lines A0 and A1 enable the input data latches
for the high, middle, or low data nibbles. The $\mu \mathrm{P}$ sends chip select (CS) and write (WR) signals to latch in each of three nibbles in three cycles when the data is valid.
Figure 7 shows a typical interface to an 8 -bit or a 16 -bit $\mu \mathrm{P}$. Connect 8 data bits from the data bus to pins D0-D7 on the MAX530. With LDAC held high, the user can load NBH or NBL + NBM in any order. Figure 8a shows the corresponding timing sequence. For fastest throughput, use Figure 8b's sequence. Address lines A0 and A1 are tied together and the DAC is loaded in 2 cycles as $8+4$. In this scheme, with LDAC held low, the DAC latch is transparent. Always load NBL and NBM first, followed by NBH.
$\overline{\mathrm{LDAC}}$ is asynchronous with respect to $\overline{\mathrm{WR}}$. If $\overline{\mathrm{LDAC}}$ is brought low before or at the same time WR goes high, LDAC must remain low for at least 50 ns to ensure the correct data is latched. Data is latched into DAC registers on LDAC's rising edge.
+5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC


Figure 5. 4-Bit $\mu \mathrm{P}$ Interface


Figure 7. 8 -Bit and 16 -Bit $\mu$ P Interface


Figure 6. 4-Bit $\mu$ P Timing Sequence


Figure 8a. 8-Bit and 16-Bit $\mu$ P Timing Sequence Using $\overline{\text { LDAC }}$

## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC



Figure 8b. 8-Bit and 16-Bit $\mu$ P Timing Sequence with $\overline{L D A C}=0$

Unipolar Configuration
The MAX530 is configured for a 0 V to +2.048 V unipolar output range by connecting ROFS and RFB to VOUT (Figure 9). The converter operates from either single or dual supplies in this configuration. See Table 3 for the DAC-latch contents (input) vs. the analog VOUT (output). In this range, 1 LSB $=$ REFIN ( $2^{-12}$ ).


Figure 9. Unipolar Configuration (OV to +2.048 V Output)

A OV to 4.096V unipolar output range is set up by connecting ROFS to AGND and RFB to VOUT (Figure 10). Table 4 shows the DAC-latch contents vs. VOUT. The MAX530 operates from either single or dual supplies in this mode. In this range, 1 LSB $=(2)($ REFIN $)\left(2^{-12}\right)=$ (REFIN)(2-11).


Figure 10. Unipolar Configuration (0V to +4.096 V Output)

## +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC

Table 3. Unipolar Binary Code Table
(OV to VREFIN Output), Gain $=1$

| INPUT | OUTPUT |  |  |
| :---: | :---: | :---: | :---: |
| 1111 | 1111 | 1111 | $\left(V_{\text {REFIN }} \frac{4095}{4096}\right.$ |
| 1000 | 0000 | 0001 | $\left(V_{\text {REFIN }} \frac{2049}{4096}\right.$ |
| 1000 | 0000 | 0000 | $\left(V_{\text {REFIN }} \frac{2048}{4096}=+V_{\text {REFIN }} / 2\right.$ |
| 0111 | 1111 | 1111 | $\left(V_{\text {REFIN }}\right) \frac{2047}{4096}$ |
| 0000 | 0000 | 0001 | $\left(V_{\text {REFIN }} \frac{1}{4096}\right.$ |
| 0000 | 0000 | 0000 | $0 V$ |

## Bipolar Configuration

A - VREFIN to $+V_{\text {REFIN }}$ bipolar range is set up by connecting ROFS to REFIN and RFB to VOUT, and operating from dual ( $\pm 5 \mathrm{~V}$ ) supplies (Figure 11). Table 5 shows the DAC-latch contents (input) vs. VOUT (output). In this range, $1 \mathrm{LSB}=\operatorname{REFIN}\left(2^{-11}\right)$.

## Four-Quadrant Multiplication

The MAX530 can be used as a four-quadrant multiplier by connecting ROFS to REFIN and RFB to VOUT and, using (1) an offset binary digital code, (2) bipolar power supplies, and (3) a bipolar analog input at REFIN within the range $V_{S S}+2 \mathrm{~V}$ to $\mathrm{V}_{\mathrm{DD}}-2 \mathrm{~V}$, as shown in Figure 12.
In general, a 12-bit DAC's output is (D)(VREFIN)(G), where " $G$ " is the gain ( 1 or 2 ) and " $D$ " is the binary representation of the digital input divided by $2^{12}$ or 4,096 . This formula is precise for unipolar operation. However, for bipolar, offset binary operation, the MSB is really a polarity bit. No resolution is lost, because there is the same number of steps. The output voltage, however, has been shifted from a range of, for example, 0 V to $4.096 \mathrm{~V}(\mathrm{G}=2)$ to a range of -2.048 V to +2.048 V .
Keep in mind that when using the DAC as a four-quadrant multiplier, the scale is skewed. The negative full scale is - VREFIN, while the positive full scale is $+V_{\text {REFIN }}$ - 1LSB.

Table 4. Unipolar Binary Code Table (OV to 2VREFIN Output), Gain = 2

| INPUT | OUTPUT |  |  |
| :---: | :---: | :---: | :---: |
| 1111 | 1111 | 1111 | $+2\left(V_{\text {REFIN }}\right) \frac{4095}{4096}$ |
| 1000 | 0000 | 0001 | $+2\left(V_{\text {REFIN }} \frac{2049}{4096}\right.$ |
| 1000 | 0000 | 0000 | $+2\left(V_{\text {REFIN }}\right) \frac{2048}{4096}=+V_{\text {REFIN }}$ |
| 0111 | 1111 | 1111 | $+2\left(V_{\text {REFIN }}\right) \frac{2047}{4096}$ |
| 0000 | 0000 | 0001 | $+2\left(V_{\text {REFIN }}\right) \frac{1}{4096}$ |
| 0000 | 0000 | 0000 | $0 V$ |

Table 5. Bipolar (Offset Binary) Code Table (-Vrefin to +Vrefin Output)

| INPUT |  |  | OUTPUT |
| :---: | :---: | :---: | :---: |
| 1111 | 1111 | 1111 | $\left(+V_{\text {REFIN }} \frac{2047}{2048}\right.$ |
| 1000 | 0000 | 0001 | $\left(+V_{\text {REFIN }} \frac{1}{2048}\right.$ |
| 1000 | 0000 | 0000 | 0 V |
| 0111 | 1111 | 1111 | $\left(-V_{\text {REFIN }}\right) \frac{1}{2048}$ |
| 0000 | 0000 | 0001 | $\left(-V_{\text {REFIN }} \frac{2047}{2048}\right.$ |
| 0000 | 0000 | 0000 | $\left(-V_{\text {REFIN }} \frac{2048}{2048}=-V_{\text {REFIN }}\right.$ |

# +5V, Low-Power, Parallel-Input, Voltage-Output, 12-Bit DAC 



Figure 11. Bipolar Configuration (-2.048V to +2.048 V Output)

## Applications Information

## Single-Supply Linearity

As with any amplifier, the MAX530's output op amp offset can be positive or negative. When the offset is positive, it is easily accounted for. However, when the offset is negative, the output cannot follow linearly when there is no negative supply. In that case, the amplifier output (VOUT) remains at ground until the DAC voltage is sufficient to overcome the offset and the output becomes positive. The resulting transfer function is shown in Figure 13.
Normally, linearity is measured after allowing for zero error and gain error. Since, in single-supply operation, the actual value of a negative offset is unknown, it cannot be accounted for during test. In the MAX530, linearity and gain error are measured from code 11 to code 4095 (see Note 2 under Electrical Characteristics). The output amplifier offset does not affect monotonicity, and these DACs are guaranteed monotonic starting with code zero. In dual-supply operation, linearity and gain error are measured from code 0 to 4095.

## Power-Supply Bypassing and Ground Management

Best system performance is obtained with printed circuit boards that use separate analog and digital ground planes. Wire-wrap boards are not recommended. The two ground planes should be connected together at the low-impedance power-supply source.
AGND and REFGND should be connected together, and then to DGND at the chip. For single-supply appli-


Figure 12. Four-Quadrant Multiplying Circuit
cations, connect VSS to AGND at the chip. The best ground connection may be achieved by connecting the AGND, REFGND, and DGND pins together and connecting that point to the system analog ground plane. If DGND is connected to the system digital ground, digital noise may get through to the DAC's analog portion.
Bypass $V_{D D}$ (and $V_{S S}$ in dual-supply mode) with a $0.1 \mu \mathrm{~F}$ ceramic capacitor connected between $\mathrm{V}_{\mathrm{DD}}$ and AGND (and between Vss and AGND). Mount the capacitors with short leads close to the device.

## AC Considerations

Digital Feedthrough
High-speed data at any of the digital input pins may couple through the DAC package and cause internal stray capacitance to appear as noise at the DAC output, even though $\overline{\text { LDAC }}$ and $\overline{\mathrm{CS}}$ are held high (see Typical Operating Characteristics). This digital feedthrough is tested by holding LDAC and $\overline{\mathrm{CS}}$ high and toggling the data inputs from all 1 s to all 0 s .

Analog Feedthrough
Because of internal stray capacitance, higher-frequency analog input signals at REFIN may couple to the output, even when the input digital code is all 0 s , as shown in the Typical Operating Characteristics graph Analog Feedthrough vs. Frequency. It is tested by setting CLR to low (which sets the DAC latches to all Os) and sweeping REFIN.

## ＋5V，Low－Power，Parallel－Input， Voltage－Output，12－Bit DAC



Figure 13．Single－Supply DAC Transfer Function

## ＿Ordering Information（continued）

| PART | TEMP．RANGE | PIN－PACKAGE | ERROR <br> （LSB） |
| :---: | :---: | :--- | :---: |
| MAX530AENG | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24Narrow Plastic DIP | $\pm 1 / 2$ |
| MAX530BENG | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 Narrow Plastic DIP | $\pm 1$ |
| MAX530AEWG | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1 / 2$ |
| MAX530BEWG | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1$ |
| MAX530AEAG | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1 / 2$ |
| MAX530BEAG | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1$ |

## ＿＿＿Chip Topography



TRANSISTOR COUNT：913； SUBSTRATE CONNECTED TO VDD． implied．Maxim reserves the right to change the circuitry and specifications without notice at any time．
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